

V <sub>CES</sub>	650V
Ι <sub>C(100°C)</sub>	20A
V <sub>CE(sat) (Typ.)</sub>	1.6V
PD	144W

#### Features

- 1) Low Collector Emitter Saturation Voltage
- 2) High Speed Switching
- 3) Low Switching Loss & Soft Switching
- 4) Built in Very Fast & Soft Recovery FRD (RFN - Series)
- 5) Pb free Lead Plating ; RoHS Compliant

#### Applications

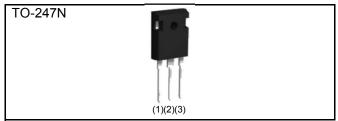
PFC

UPS

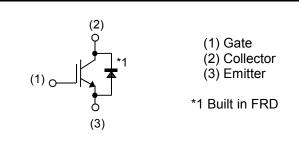
Power Conditioner

IH

#### Outline



#### Inner Circuit



#### Packaging Specifications

	Packaging	Tube
	Reel Size (mm)	-
Type	Tape Width (mm)	-
Туре	Basic Ordering Unit (pcs)	450
	Packing code	C11
	Marking	RGTH40TS65D

#### •Absolute Maximum Ratings (at T<sub>C</sub> = 25°C unless otherwise specified)

	1 0		,	
Parameter		Symbol	Value	Unit
Collector - Emitter Voltage		V <sub>CES</sub>	650	V
Gate - Emitter Voltage		V <sub>GES</sub>	±30	V
Collector Current	T <sub>C</sub> = 25°C	Ι <sub>C</sub>	40	А
Collector Current	T <sub>C</sub> = 100°C	Ι <sub>C</sub>	20	А
Pulsed Collector Current		I <sub>CP</sub> *1	80	А
Diode Forward Current	T <sub>C</sub> = 25°C	I <sub>F</sub>	35	А
Diode Forward Current	T <sub>C</sub> = 100°C	I <sub>F</sub>	20	А
Diode Pulsed Forward Current	I <sub>FP</sub> <sup>*1</sup>	80	А	
$T_c = 25^{\circ}C$		P <sub>D</sub>	144	W
Power Dissipation	T <sub>C</sub> = 100°C	P <sub>D</sub>	72	W
Operating Junction Temperature		Tj	-40 to +175	°C
Storage Temperature	T <sub>stg</sub>	-55 to +175	°C	
*1 Pulse width limited by T.		•	•	

\*1 Pulse width limited by T<sub>jmax.</sub>

#### •Thermal Resistance

Parameter	Symbol	Values			Unit
Farameter	Symbol	Min.	Тур.	Max.	Unit
Thermal Resistance IGBT Junction - Case	$R_{\theta(j-c)}$	-	-	1.04	°C/W
Thermal Resistance Diode Junction - Case	$R_{\theta(j-c)}$	-	-	2.28	°C/W

### ●IGBT Electrical Characteristics (at T<sub>j</sub> = 25°C unless otherwise specified)

Parameter	Symbol Conditions -		Values			Unit	
Faranieler	Symbol	Conditions	Min. Typ.		Max.	Unit	
Collector - Emitter Breakdown Voltage	BV <sub>CES</sub>	I <sub>C</sub> = 10μΑ, V <sub>GE</sub> = 0V	650	-	-	V	
Collector Cut - off Current	I <sub>CES</sub>	V <sub>CE</sub> = 650V, V <sub>GE</sub> = 0V	-	-	10	μA	
Gate - Emitter Leakage Current	I <sub>GES</sub>	V <sub>GE</sub> = ±30V, V <sub>CE</sub> = 0V	-	-	±200	nA	
Gate - Emitter Threshold Voltage	V <sub>GE(th)</sub>	V <sub>CE</sub> = 5V, I <sub>C</sub> = 13.3mA	4.5	5.5	6.5	V	
Collector - Emitter Saturation Voltage	V <sub>CE(sat)</sub>	I <sub>C</sub> = 20A, V <sub>GE</sub> = 15V T <sub>j</sub> = 25°C T <sub>j</sub> = 175°C	-	1.6 2.1	2.1	V	



## •IGBT Electrical Characteristics (at $T_j = 25^{\circ}C$ unless otherwise specified)

Deremeter	Symbol Conditions		Values			1.1	
Parameter	Symbol	Conditions	Min. Typ. N		Max.	Unit	
Input Capacitance	C <sub>ies</sub>	V <sub>CE</sub> = 30V	-	1060	-		
Output Capacitance	C <sub>oes</sub>	V <sub>GE</sub> = 0V	-	47	-	pF	
Reverse Transfer Capacitance	C <sub>res</sub>	f = 1MHz	-	18	-		
Total Gate Charge	$Q_g$	V <sub>CE</sub> = 300V	-	40	-		
Gate - Emitter Charge	$Q_{ge}$	I <sub>C</sub> = 20A	-	9	-	nC	
Gate - Collector Charge	$Q_{gc}$	V <sub>GE</sub> = 15V	-	15	-		
Turn - on Delay Time	t <sub>d(on)</sub>	I <sub>C</sub> = 20A, V <sub>CC</sub> = 400V	-	22	-		
Rise Time	t <sub>r</sub>	V <sub>GE</sub> = 15V, R <sub>G</sub> = 10Ω	-	25	-		
Turn - off Delay Time	$t_{d(off)}$	T <sub>j</sub> = 25°C	-	73	-	ns	
Fall Time	t <sub>f</sub>	Inductive Load	-	48	-		
Turn - on Delay Time	t <sub>d(on)</sub>	I <sub>C</sub> = 20A, V <sub>CC</sub> = 400V	-	22	-		
Rise Time	t <sub>r</sub>	V <sub>GE</sub> = 15V, R <sub>G</sub> = 10Ω	-	25	-		
Turn - off Delay Time	$t_{d(off)}$	T <sub>j</sub> = 175°C	-	83	-	ns	
Fall Time	t <sub>f</sub>	Inductive Load	-	58	-		
		I <sub>C</sub> = 80A, V <sub>CC</sub> = 520V		-	-		
Reverse Bias Safe Operating Area RBS		V <sub>P</sub> = 650V, V <sub>GE</sub> = 15V	FULL SQUARE		-		
		R <sub>G</sub> = 60Ω, T <sub>j</sub> = 175°C					

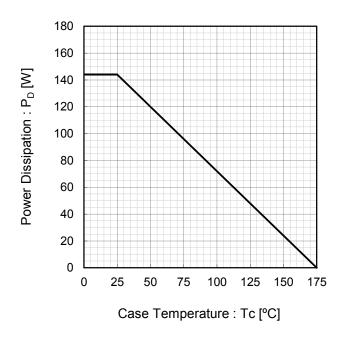


## •FRD Electrical Characteristics (at $T_j = 25^{\circ}C$ unless otherwise specified)

Deremeter	Cumhal	Conditions	Values			Lincit	
Parameter	Parameter Symbol Conditions		Min.	Тур.	Max.	Unit	
Diode Forward Voltage	V <sub>F</sub>	I <sub>F</sub> = 20A T <sub>j</sub> = 25°C T <sub>j</sub> = 175°C	-	1.45 1.25	1.9 -	V	
Diode Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> = 20A	-	58	-	ns	
Diode Peak Reverse Recovery Current	I <sub>rr</sub>	V <sub>CC</sub> = 400V di <sub>F</sub> /dt = 200A/µs T <sub>j</sub> = 25°C	-	6.3	-	А	
Diode Reverse Recovery Charge	Q <sub>rr</sub>		-	0.20	-	μC	
Diode Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> = 20A	-	256	-	ns	
Diode Peak Reverse Recovery Current	I <sub>rr</sub>	V <sub>CC</sub> = 400V di <sub>F</sub> /dt = 200A/µs	-	10.4	-	А	
Diode Reverse Recovery Charge	Q <sub>rr</sub>	T <sub>j</sub> = 175°C	-	1.35	-	μC	

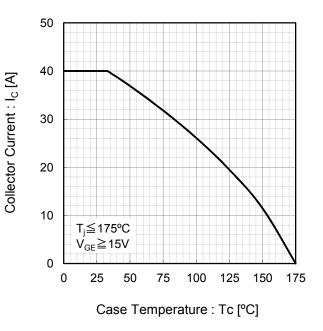






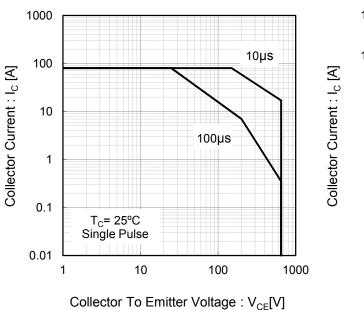
#### Fig.1 Power Dissipation vs. Case Temperature

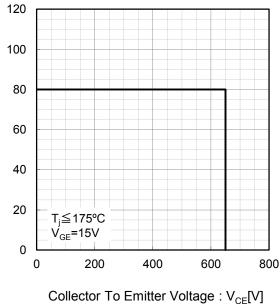
#### Fig.2 Collector Current vs. Case Temperature

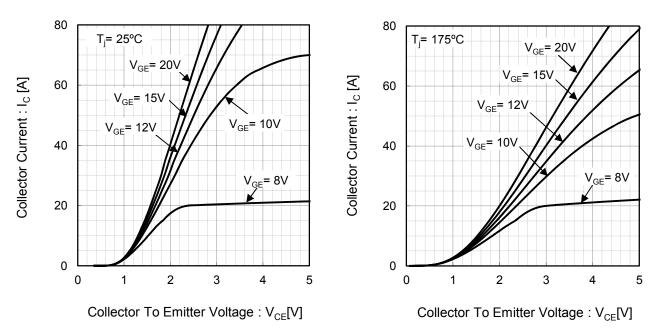


#### Fig.3 Forward Bias Safe Operating Area

#### Fig.4 Reverse Bias Safe Operating Area







#### Fig.5 Typical Output Characteristics

Fig.6 Typical Output Characteristics

#### Fig.7 Typical Transfer Characteristics

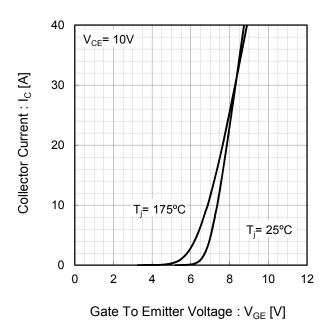
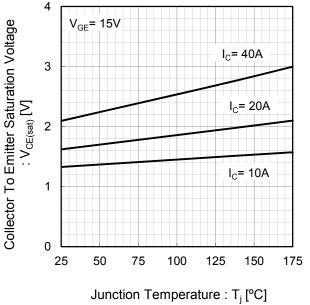


Fig.8 Typical Collector To Emitter Saturation Voltage vs. Junction Temperature



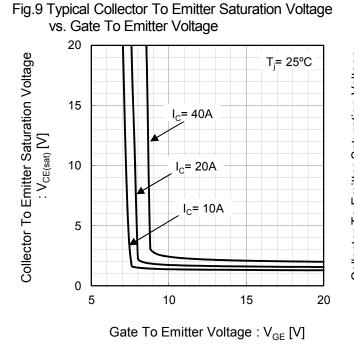
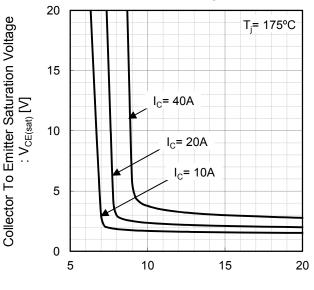


Fig.10 Typical Collector To Emitter Saturation Voltage vs. Gate To Emitter Voltage



Gate To Emitter Voltage : V<sub>GE</sub> [V]

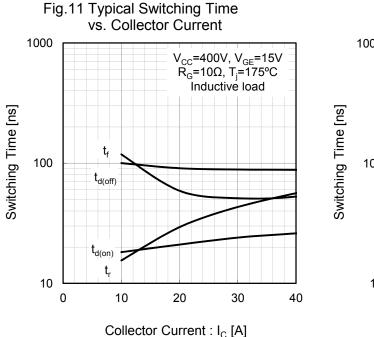
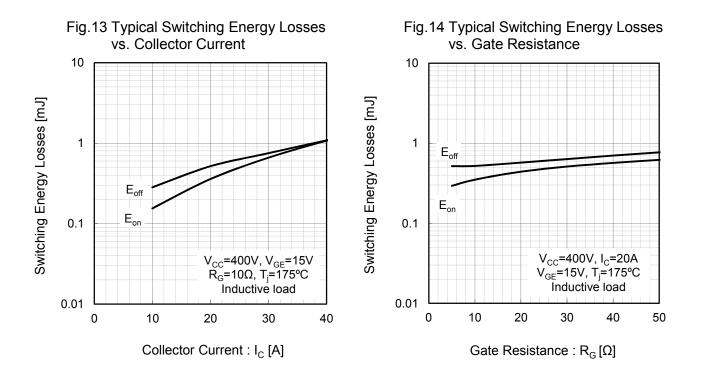


Fig.12 Typical Switching Time vs. Gate Resistance 1000 V<sub>CC</sub>=400V, I<sub>C</sub>=20A V<sub>GE</sub>=15V, T<sub>j</sub>=175°C Inductive load t<sub>d(off)</sub> 100 tf t, t<sub>d(on)</sub> 10 10 20 30 40 50 0 Gate Resistance :  $R_G[\Omega]$ 

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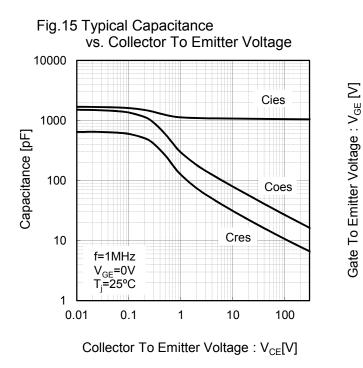
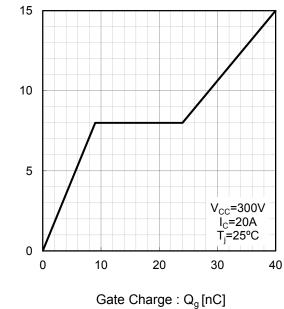
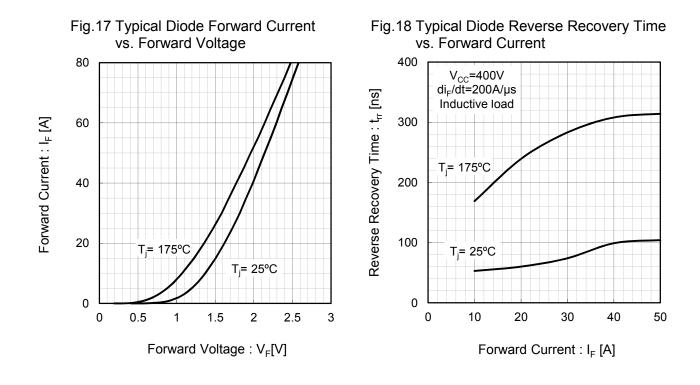
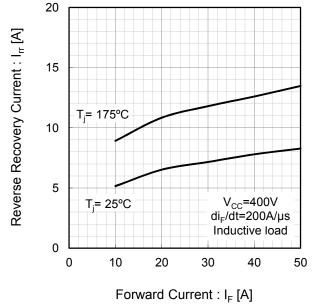


Fig.16 Typical Gate Charge

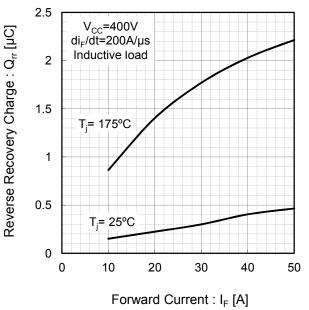




# Fig.19 Typical Diode Reverse Recovery Current vs. Forward Current



# Fig.20 Typical Diode Reverse Recovery Charge vs. Forward Current



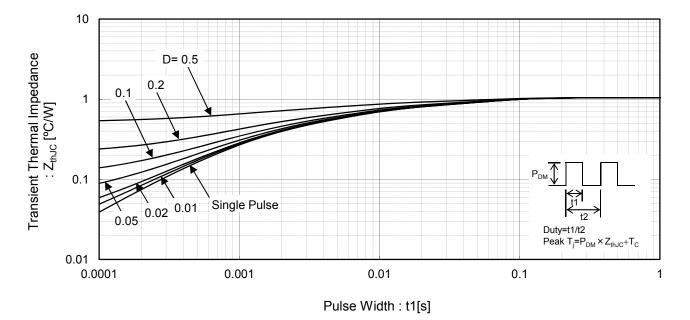


Fig.21 IGBT Transient Thermal Impedance



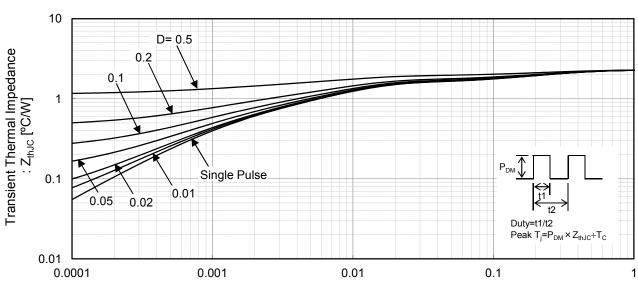


Fig.22 Diode Transient Thermal Impedance

Pulse Width : t1[s]



#### ●Inductive Load Switching Circuit and Waveform

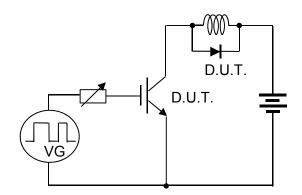


Fig.23 Inductive Load Circuit

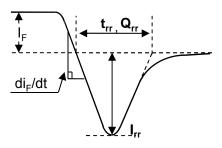


Fig.25 Diode Reverce Recovery Waveform

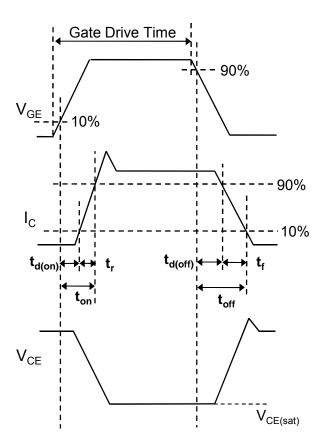


Fig.24 Inductive Load Waveform



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Part Number	RGTH40TS65D
Package	TO-247N
Unit Quantity	450
Minimum Package Quantity	450
Packing Type	Bulk
Constitution Materials List	inquiry
RoHS	Yes



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